

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comm en ts	Error r De fi ni ti on	Error rs
1	BRS	L2	2	(partial\$4 or select\$5) near (bond\$4 or join\$4) with wafer with oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:34			
2	BRS	L3	98	(partial\$4 or select\$5) with (bond\$4 or join\$4) with wafer with oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:20			
3	BRS	L4	16	(partial\$4 or select\$5) near3 (bond\$4 or join\$4) with wafer with oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:17			
4	BRS	L5	31	(partial\$4 or select\$5) with (bond\$4 or join\$4) with wafer with oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and plan\$7 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:21			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comm en ts	Error r De fi ni ti on	Error rs
5	BRS	L7	22	( "3332137"   "3475664"   "3579055"   "3623219"   "3832247"   "5091331"   "5169472"   "5183769"   "5385632") .PN. OR ("5654226") .URPN.	US - PGPUB; USPAT; USOCR	2005/11/25 01:28			
6	BRS	L9	100	(partial\$4 or select\$5 or segment\$4) with (bond\$4 or join\$4) with oxide with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:44			
7	BRS	L10	31	(partial\$4 or select\$5 or segment\$4) with (bond\$4 or join\$4) with oxide and releas\$ with (device or circuit) and wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:51			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
8	BRS	L11	43	(bond\$4 or join\$4) with oxide with wafer and releas\$ with (device or circuit) with (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:51			
9	BRS	L12	16	("438"/464).ccls. and (bond\$4 or join\$4) with wafer with oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 01:59			
10	BRS	L15	62	("438"/\$).ccls. and (bond\$4 or join\$4) near wafer near oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 02:00			
11	BRS	L16	62	("438"/\$).ccls. and (partial\$4 or select\$5 or segment\$4) with (bond\$4 or join\$4) with wafer with oxide and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/25 02:03			